

RZ/FIVE

PACKAGE OUTLINE DRAWING

June 2022 REV1.00

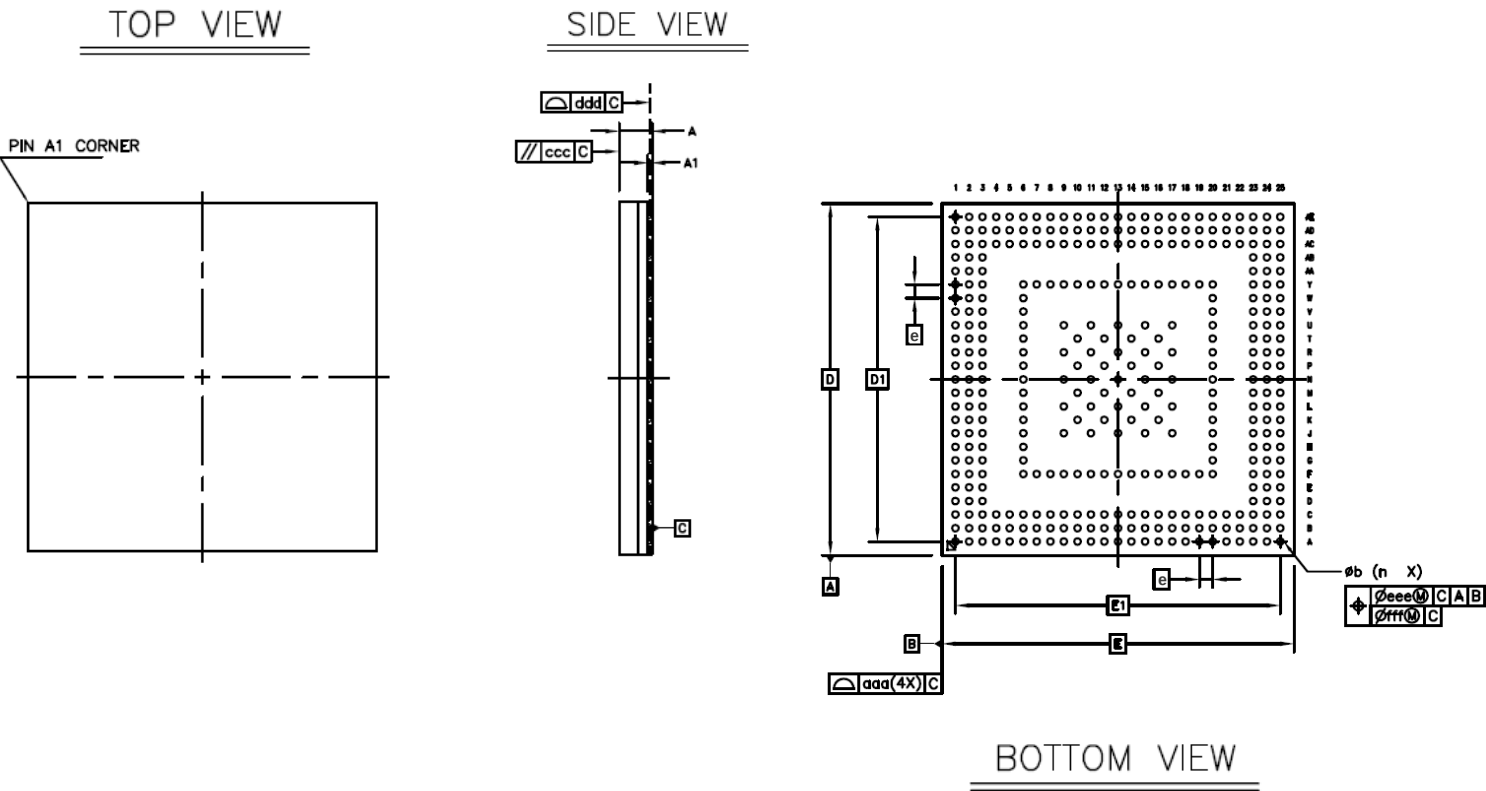
MPU PRODUCT DEPARTMENT

ENTERPRISE INFRASTRUCTURE BUSINESS DIVISION

RENESAS ELECTRONICS CORPORATION

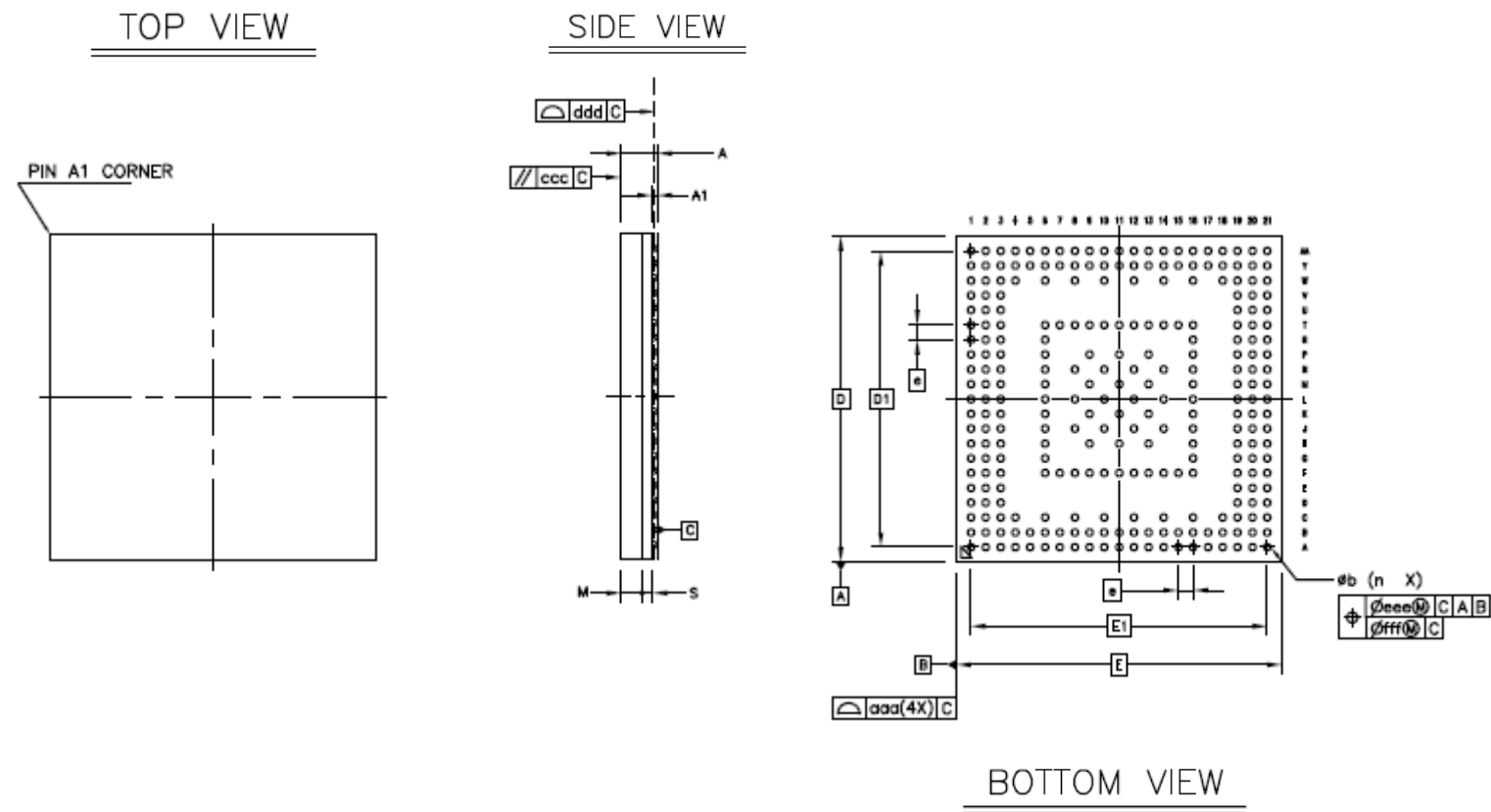
EPMP-IMB-22-0157-1

Package outline (13mm body) RZ/Five



			Common Dimensions		
Parameter		Symbol	MIN	NOM	MAX
Body size	X	E	13		
	Y	D	13		
Ball pitch		e	0.500		
Total Thickness		A	1.100	1.250	1.400
Stand Off		A1	0.110	-	0.210
Ball Width		b	0.200	-	0.300
Pakeage Edge Tolerance		aaa	0.150		
Mold Parallelism		ccc	0.200		
Coplanarity		ddd	0.080		
Ball offset (Package)		eee	0.150		
Ball offset (Ball)		fff	0.080		
Ball count		n	361		
Edge Ball Center to Center	X	E1	12.000		
	Y	D1	12.000		

Package outline (11mm body) RZ/Five



		Common Dimensions		
Parameter	Symbol	MIN	NOM	MAX
Body size	X	11		
	Y	11		
Ball pitch	e	0.500		
Total Thickness	A	1.100	1.250	1.400
Stand Off	A1	0.110	-	0.210
Ball Width	b	0.200	-	0.300
Pakeage Edge Tolerance	aaa	0.150		
Mold Parallelism	ccc	0.200		
Coplanarity	ddd	0.080		
Ball offset (Package)	eee	0.150		
Ball offset (Ball)	fff	0.080		
Ball count	n	266		
Edge Ball Center to Center	X	E1	10.000	
	Y	D1	10.000	

REVISION HISTORY

Rev.	Date	Description
1.0	June. 2022	Initial release

[Renesas.com](https://www.renesas.com)